

Revision History

Rev.No.	Description of revise	Date	Approved by	Checked by	Issued by
1	First Edition	Jul.29,2013	Y.Takahashi	T.Nitoube	M.Konno
2	•Frequency Addition. 49152kHz	Jan,24,2014	Y.Takahashi	T. Nitoube	M.Hashimoto

[PART NUMBER LIST]

Nominal Frequency (MHz)	KYOCERA Part Number	ESR (Ω)	Nominal Frequency Code
10	CX3225GB10000P0HPQCC	300	10000
12	CX3225GB12000P0HPQCC	250	12000
12.288	CX3225GB12288P0HPQCC	250	12288
13	CX3225GB13000P0HPQCC	250	13000
13.56	CX3225GB13560P0HPQCC	250	13560
14.31818	CX3225GB14318P0HPQCC	100	14318
14.7456	CX3225GB14745P0HPQCC	100	14745
16	CX3225GB16000P0HPQCC	80	16000
16.384	CX3225GB16384P0HPQCC	80	16384
18.432	CX3225GB18432P0HPQCC	80	18432
19.2	CX3225GB19200P0HPQCC	80	19200
20	CX3225GB20000P0HPQCC	60	20000
22.5792	CX3225GB22579P0HPQCC	60	22579
24	CX3225GB24000P0HPQCC	60	24000
24.576	CX3225GB24576P0HPQCC	60	24576
25	CX3225GB25000P0HPQCC	60	25000
27	CX3225GB27000P0HPQCC	50	27000
27.12	CX3225GB27120P0HPQCC	50	27120
30	CX3225GB30000P0HPQCC	50	30000
32	CX3225GB32000P0HPQCC	50	32000
33.333	CX3225GB33333P0HPQCC	50	33333
36	CX3225GB36000P0HPQCC	50	36000
38.4	CX3225GB38400P0HPQCC	50	38400
40	CX3225GB40000P0HPQCC	50	40000
48	CX3225GB48000P0HPQCC	50	48000
49.152	CX3225GB49152P0HPQCC	50	49152
50	CX3225GB50000P0HPQCC	50	50000
54	CX3225GB54000P0HPQCC	50	54000



1. APPLICATION

This specification sheet is applied to quartz crystal “CX3225GB”

2. KYOCERA PART NUMBER

Refer to K1101-13754-432 3/11 KYOCERA Part Number

3. RATINGS

Items	SYMB.	Rating	Unit	Remarks
Operating Temperature	Topr	-40~+85	°C	
Storage Temperature Range	Tstg	-40~+85	°C	

4. CHARACTERISTICS

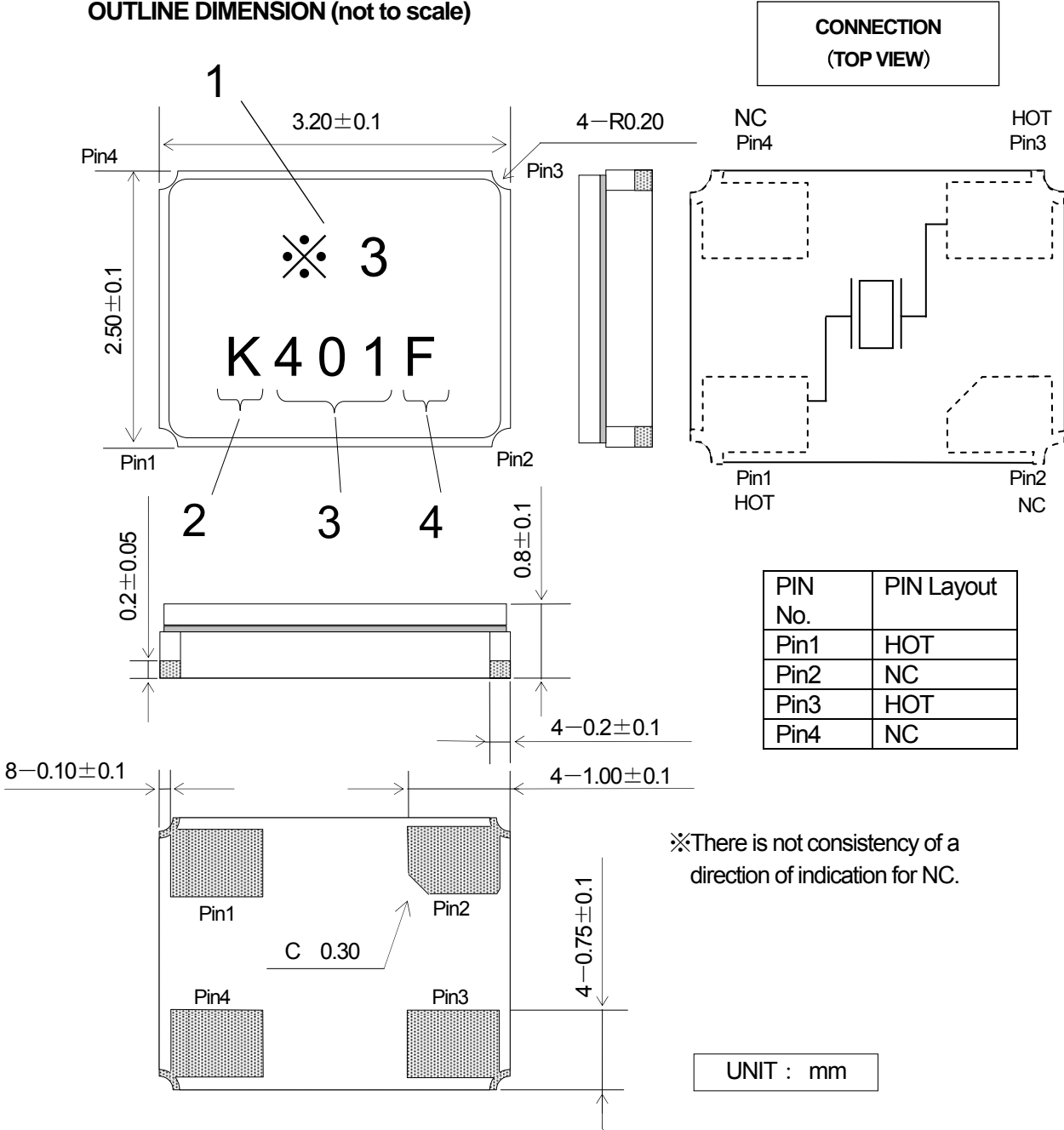
4-1 ELECTRICAL CHARACTERISTICS

Items	Electrical Specification					Test Condition	Remarks
	SYMB.	Min.	Typ.	Max.	Unit		
Mode of Vibration		Fundamental					
Nominal Frequency	F0		※1		MHz		
Nominal Temperature	T _{NOM}		+25		°C		
Load Capacitance	CL		18.0		pF		
Frequency Tolerance	df/F	-20.0		+20.0	PPM	+25±3°C	
Frequency Temperature Characteristics	df/F	-30.0		+30.0		-40~+85°C	
Frequency Aging Rate		-5.0		+5.0		1 year	+25±3°C
Equivalent Series Resistance	ESR			※2	Ω		
Drive Level	Pd	0.01		100	μW		
Insulation Resistance	IR	500			MΩ	100V(DC)	

※1 Refer to K1101-13754-432 3/11 Nominal Frequency

※2 Refer to K1101-13754-432 3/11 ESR

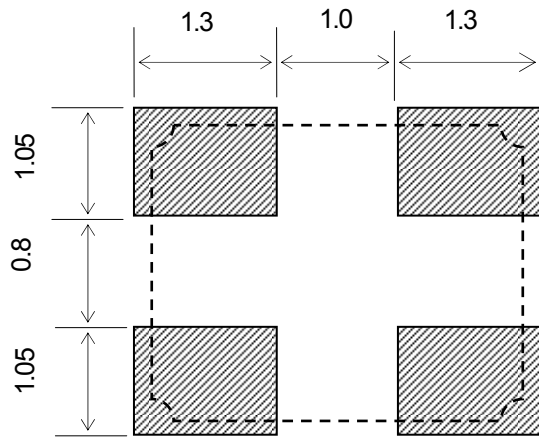
5. APPEARANCES, PHYSICAL DIMENSION
OUTLINE DIMENSION (not to scale)



MARKING

- | | |
|--------------------------|--|
| 1 Nominal Frequency | Move the number of maximum indication beams of the frequency to five digits, and omit less than kHz. |
| 2 Identification | |
| 3 Date Code | Year···LAST 1 DIGIT of YEAR AND WEEK
(Ex) Jan. 1, 2014 → 401 |
| 4 Manufacturing Location | F··KYOCERA Crystal Device Philippines, Inc |

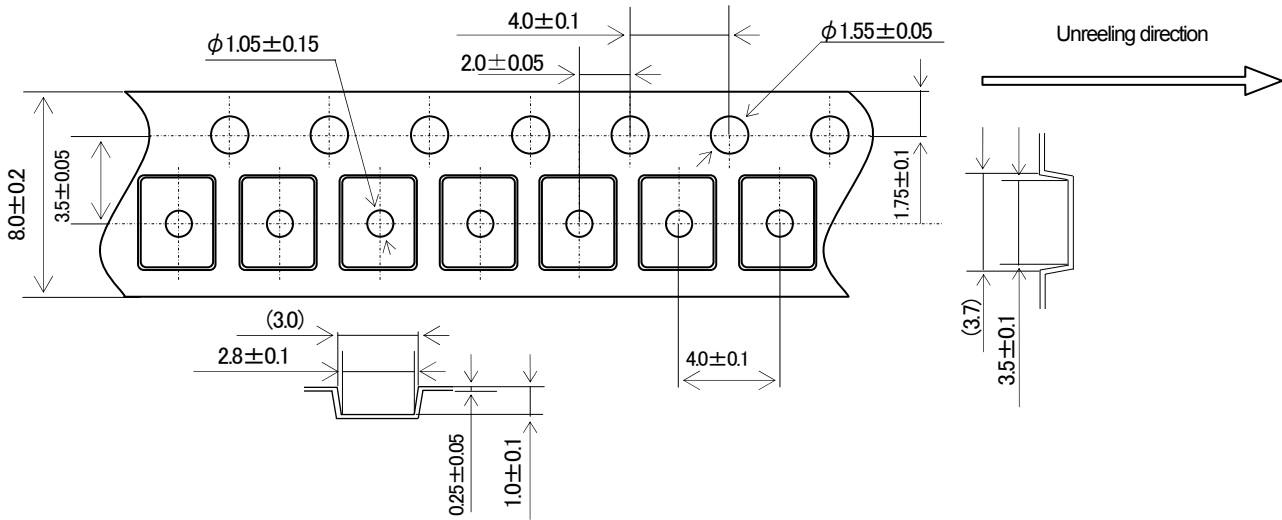
※3 Refer to K1101-13754-432 3/11 Nominal Frequency Code.
The font of marking is reference.

6. RECOMMENDED LAND PATTERN (not to scale)

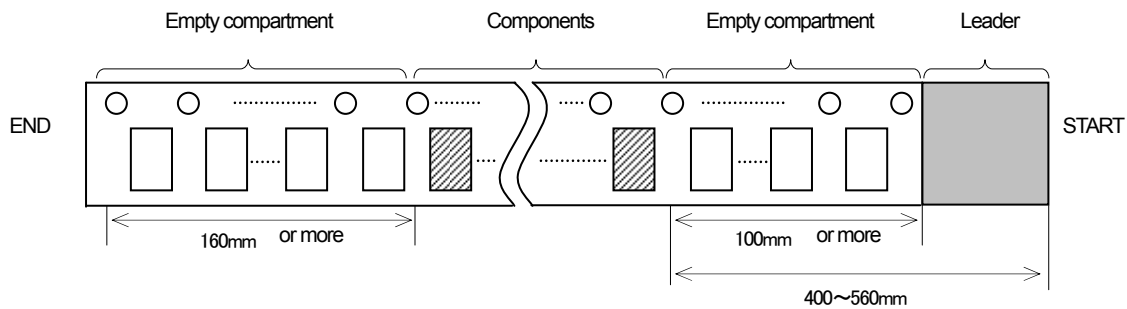
UNIT : mm

7.TAPING & REEL 梱包補助材

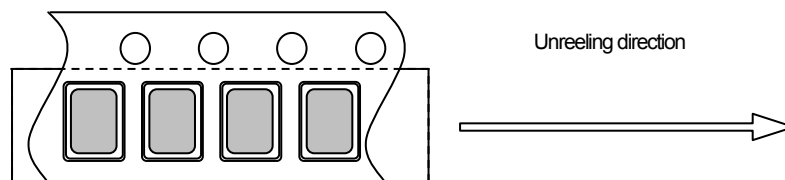
7-1.Dimensions



7-2.Leader and trailer tape

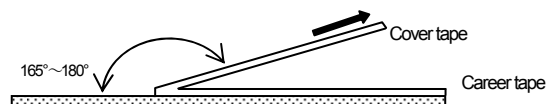


7-3.Direction (The direction shall be seen from the top cover tape side)

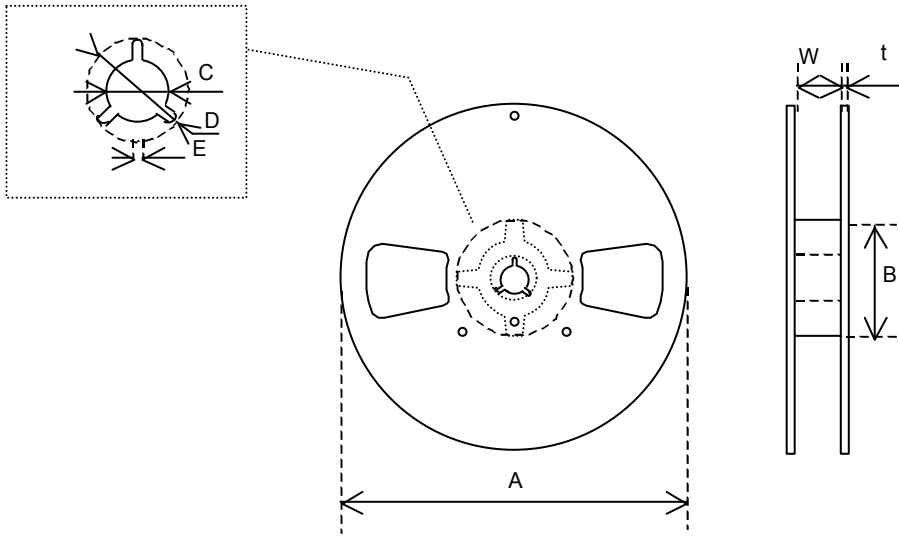


7-4.Specification

1. Material of the carrier tape shall be PS (ESD).
2. Material of the seal tape shall be polyester(ESD).
3. The seal tape shall not cover the sprocket holes. And not protrude from the carrier tape.
4. Tensile strength of the tape : 10N or more.
5. The R of the corner without designation is 0.2RMAX.
6. Disalignment between centers of the cavity and sprocket hole shall be 0.05mm or less.
7. Cumulative pitch tolerance of "P₀" shall be ± 0.2 mm at 10 pitches.
8. The number of lack is 0.1% of 1 reel total part number (the number of the table letters) or the part following whose 1 either is big. (But, the thing which lack of the continuance is not in.)
9. The marking on parts is not fixed its direction, its electrical characteristic is equal.
10. Peeling force of the seal tape: 0.1 to 1.0N.



7-5.Reel specifications



(Nonconductor type Reel)

In the case of $\Phi 180$ Reel (3000 pcs max, every 1000 pcs)

	A	B	C	D
Dimension	$\phi 180 +0/-1.5$	$\phi 60 +1/-0$	$\phi 13 \pm 0.2$	$\phi 21 \pm 0.8$
Symbol	E	W	t	
Dimension	2.0 ± 0.5	9 ± 1	2.0 ± 0.5	

(Unit : mm)

8.6 Resistance to Moisture

Test condition

The quartz crystal unit shall be stored at a temperature of $60 \pm 2^\circ\text{C}$ with relative humidity of 90% to 95% for 240 h. Then it shall be subjected to standard atmospheric conditions for 1h, after which measurements shall be made

8.7 Soldering condition

- 1.) Material of solder
 - Kind ... lead free solder paste
 - Melting point ... $+220 \pm 5^\circ\text{C}$

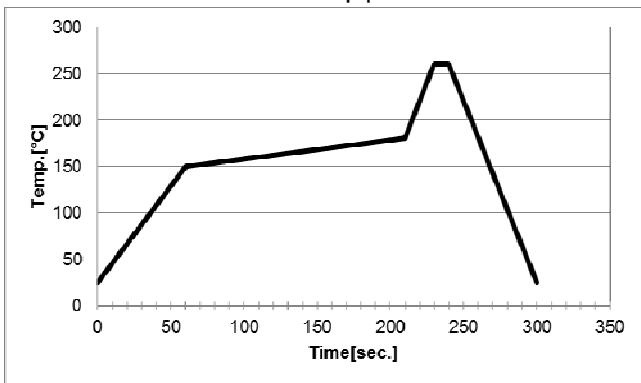
2.) Reflow temp.profile

	Temp [$^\circ\text{C}$]	Time[sec]
Preheating	+150 to +180	150 (typ.)
Peak	$+260 \pm 5$	10 (max.)
Total	—	300 (max.)

Frequency shift : $\pm 2\text{ppm}$

- 3.) Hand Soldering + 350°C 3 sec MAX
- 4.) Reflow Times 2 times

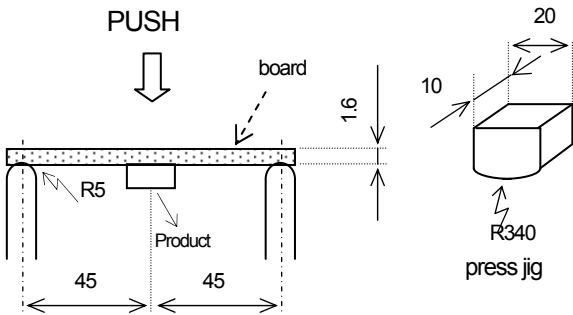
Reflow temp.profile



8.8 Intensity for bending in circuit board

Solder this product in center of the circuit board of $40\text{mm} \times 100\text{mm}$, and add the deflection of 3mm as the bottom figure.

Test board : $t=1.6\text{mm}$



UNIT : mm

9. Cautions for use

(1) Automatic mounting machine use

Please use after affirmation that select the mounting machine model with a shock small if possible in the case of use of an automatic mounting machine, and it does not have breakage. There is a risk of a quartz crystal unit breakage occurring and not functioning normally by too much shock etc..

(2) Conformity of a circuit

In case of use of an oscillation circuit, please insert in a quartz crystal unit in series resistance 5 time as many as the standard value of equivalent in-series resistance, and confirm oscillating. Please remove resistance which inserted after the notes above-mentioned examination in the quartz crystal unit in series, and use it.

(3) After making the Quartz Crystal mount on a printed circuit board ,if it is required to divide the printed circuit board into another one, use it with attentive confirmation so that a warp caused by this dividing might not affect any damage. When designing a printed circuit board as well as handling the mounting As much as possible. The quartz crystal shall be passed through the reflow furnace. Then it shall be subjected to standard atmospheric conditions, after which cleaning shall be made.

10. Storage conditions

Storage at prolonged high temperature or low temperature and the storage by high humidity cause degradation of frequency accuracy, and degradation of soldering nature. Storage is performed at the temperature of 18-30 degrees C, and the humidity of 20-70 Percent in the state of packing, and a term is 6 months.

11. Manufacturing location

KYOCERA Crystal Device Philippines, Inc.

12. Quality Assurance

Kyocera Crystal Device Quality Assurance Division

13. Quality guarantee

When the failure by the responsibility of our company occurs clearly after delivery within 1 year, a substitute article etc. is appropriated gratuitously and this is guaranteed. However, when passing 1 year after delivery, there is a case where I am allowed to consider as onerous repair after both consultation.

14. Others

When any questions and opinions are in the written matter of these delivery specifications, I will ask connection of you from the our company issue day within 45 days. In a connection no case, a written matter is consented to it and employed within a term.